

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	11	"6540414".pn. "6738265".pn. "6832856".pn. "20050152701" "6160647".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 13:14
L4	4	L3 and housing with shield	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 13:27
L5	1	L3 and housing with nose	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 13:27
S1	24	("20030118293" "6335869" "636992 4" "6407932" "6459517" "6511117" "6607308" "6609838" "6634803" " 6659655" "6666589").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 20:02
S2	1	paplawski	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 14:15
S3	1481	385/92.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:35
S4	7	optic\$4 with module with (((electro\$1magnetic (electro adj magnetic)) adj interference) emi) adj shield) with hous\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 14:20
S7	1	S4 and ((small adj (form\$1factor (form adj factor)) adj pluggable) sfp)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 14:22
S8	0	S4 and ((gigabit adj interface adj converter) gbic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 14:23
S9	0	S4 and ("1x9" ("1" adj "x" adj "9"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 14:30

S10	49	S3 and EMI adj shield	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:35
S11	0	S10 and mesh	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 13:30
S12	8	S10 and grid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 14:31
S13	1	S10 and net	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 14:33
S15	3	S10 and hous\$3 with (injection adj mold\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:38
S16	7	S10 and (EMI adj shield) with conduct\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 14:36
S17	12	EMI adj shield with conduct\$3 near3 mesh	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 13:28
S18	44	S10 and module	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:36
S19	7	housing with floor with (side\$1wall (side adj wall)) with nose	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:39
S20	0	S10 and hous\$3 with floor with (side\$1wall\$1 (side adj wall))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:39

S21	7	housing with floor with (side\$1wall\$1 (side adj wall)) with nose	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:39
S22	0	S10 and hous\$3 with floor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:39
S23	0	S10 and hous\$3 with (side\$1wall\$1 (side adj wall))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:40
S24	10	S10 and hous\$3 with nose	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 14:34
S25	5	S10 and hous\$3 with (non\$1conduct\$3 ((non "not") adj conduct\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:42
S26	137	(opto\$electr\$4 opto adj electr\$4 electro\$1optic\$4 electro adj optic\$4) adj (sub\$1assembly sub adj assembly)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:44
S27	239	(opto\$electr\$4 opto adj electr\$4 electro\$1optic\$4 electro adj optic\$4 eo oe) adj (sub\$1assembly sub adj assembly)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:47
S28	27	S27 with hous\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:46
S29	0	S28 with EMI adj shield	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 14:38
S30	0	S27 with ((first near3 hous\$3) and (second near3 hous\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:46

S31	0	S27 with (second near3 hous\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:47
S32	0	S27 with (circuit adj board) with (connector adj interface)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:48
S33	45	S27 with (circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:48
S34	3	S27 with (circuit adj board) with interface	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:49
S35	0	S27 with (circuit adj board) with interface with (lc sc mtrj)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:49
S36	0	S27 with (circuit adj board) with (lc sc mtrj)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:49
S37	2690	interface with (lc sc mtrj)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 15:50
S38	11	S37 with (circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 17:02
S39	12	EMI adj shield with conduct\$3 near3 mesh	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 18:17
S40	0	S39 with inject\$3 near3 mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 18:17

S41	41	EMI adj shield with mesh	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 09:22
S42	0	S41 with inject\$3 near3 mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 18:18
S43	1481	385/92.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 18:18
S44	49	S43 and EMI adj shield	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 18:18
S45	17	S44 and injection adj mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 18:18
S46	0	S45 and mesh	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 18:18
S47	1481	385/92.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 19:44
S49	49	S47 and EMI adj shield	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 19:55
S50	17	S48 and injection adj mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 19:52
S51	2	S49 and inser\$4 near3 mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 19:54

S52	7	optic\$4 with module with (((electro\$1magnetic (electro adj magnetic)) adj interference) emi) adj shield) with hous\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 19:54
S53	0	S52 and inser\$4 near3 mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 19:55
S54	1	S52 and mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 19:57
S55	27	S49 and mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 19:55
S56	0	S47 and (EMI adj shield) with hous\$3 with mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 19:56
S57	0	S47 and (EMI adj shield) same hous\$3 same mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 19:56
S58	23	S47 and (EMI adj shield) and hous\$3 and mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 19:56
S59	21	EMI adj shield with hous\$3 with mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 19:59
S63	0	S59 and mesh\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 20:00
S64	1	S59 and net\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 20:00

S65	24	("20030118293" "6335869" "6369924" "6407932" "6459517" "6511117" "6607308" "6609838" "6634803" "6659655" "6666589").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 20:02
S66	0	S65 and EMI adj shield with hous\$3 with mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 20:02
S67	8	S65 and EMI adj shield with hous\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 20:03
S68	0	S65 and EMI adj shield with hous\$3 and mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 20:03
S69	3	S65 and mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/29 20:03
S70	1484	385/92.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 09:12
S71	49	S70 and EMI adj shield	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 09:20
S72	44	S71 and hous\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 09:21
S73	4	S71 and second adj housing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 09:21
S74	41	EMI adj shield with mesh	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 09:26

S75	1	EMI adj shield with mesh with hous\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 09:24
S76	13	EMI adj shield with matrix	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 09:32
S77	1	EMI adj shield with matrix with hous\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 09:26
S78	1786	361/818.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 09:32
S79	13	S78 and conduct\$3 with (mesh and (finger pin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 09:34
S80	5	S79 and hous\$3 with EMI near3 shield\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 10:46
S81	12	EMI adj shield with conduct\$3 near3 mesh	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 13:28
S82	4	S81 and hous\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 13:29
S83	0	S81 and (optic\$4 near3 fiber)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 13:29
S84	2	S81 and fiber	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 13:30

S85	1484	385/92.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 13:30
S86	49	S85 and EMI adj shield	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 13:30
S87	1	S86 and matrix	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 13:30
S88	49	S85 and EMI adj shield	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 13:58
S89	27	S86 and mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 13:58
S90	0	S85 and EMI adj shield with mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 13:59
S92	0	S85 and EMI adj shield same mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 13:59
S93	129	S85 and hous\$3 with mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 13:59
S94	10	S86 and hous\$3 with mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 14:00
S95	10	S86 and hous\$3 with nose	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 14:34

S96	1	S86 and hous\$3 with nose with receptacle	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 14:35
S97	239	(opto\$electr\$4 opto adj electr\$4 electro\$1optic\$4 electro adj optic\$4 eo oe) adj (sub\$1assembly sub adj assembly)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 14:38
S98	27	S97 with hous\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 14:38
S99	0	S98 with shield	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 14:38
S10 0	0	S98 and EMI adj shield	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 14:38
S10 1	4	S98 and shield	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 14:38
S10 2	11	"6540414".pn. "6738265".pn. "6832856".pn. "20050152701" "6160647".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/30 17:31
S10 3	4	S102 and shield with hous\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 10:15
S10 4	11	"6540414".pn. "6738265".pn. "6832856".pn. "20050152701" "6160647".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 11:32
S10 5	4	S104 and shield with hous\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 10:16

S10 6	1	S105 and subassembly with circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 10:16
S10 7	1	S105 and subassembly same circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 10:16
S10 8	2	S105 and subassembly and circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 10:26
S10 9	2	S105 and subassembly with housing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 10:28
S11 0	0	S105 and transducer with housing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 10:28
S11 1	3	S105 and transceiver with housing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 10:29
S11 2	1	S105 and transceiver with housing with circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 10:29
S11 3	2	S105 and transceiver with housing same circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 10:36
S11 4	2	S105 and transceiver with circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 10:36
S11 5	3	S105 and transceiver same circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 10:38

S11 6	2	S105 and transceiver same circuit adj board same connect\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 10:38
S11 7	1	S105 and device with opening	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 10:52
S11 8	1	S104 and housing with wall	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 13:07
S11 9	2	S104 and sc	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 11:35
S12 0	2	S104 and (lc sc mt\$1rj)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/31 11:35

Day : Wednesday

Date: 8/31/2005

Time: 14:02:52

PALM INTRANET

Inventor Name Search Result

Your Search was:

Last Name = SCHWIEBERT

First Name = MATTHEW

Application#	Patent#	Status	Date Filed	Title	Inventor Name
08496553	Not Issued	161	06/29/1995	FLIP CHIP USING CONDUCTIVE LIQUID INTERCONNECT AND METHOD FOR ASSEMBLING SAME	SCHWIEBERT, MATTHEW
08787615	6084494	150	01/23/1997	SHUNTABLE MAGNETIC MASK SUPPORT APPARATUS	SCHWIEBERT, MATTHEW
09829453	6414847	150	04/09/2001	INTEGRAL DIELECTRIC HEATSPREADER	SCHWIEBERT, MATTHEW
09822910	Not Issued	161	03/29/2001	Pluggable transceiver delatch	SCHWIEBERT, MATTHEW K.
10808672	Not Issued	30	03/24/2004	Integral insert molded fiber optic transceiver electromagnetic interference shield	SCHWIEBERT, MATTHEW K.
11076601	Not Issued	20	03/10/2005	Impedance matching external component connections with uncompensated leads	SCHWIEBERT, MATTHEW K.
11129138	Not Issued	30	05/13/2005	Monolithic living hinge small form factor transceiver bail-delatch	SCHWIEBERT, MATTHEW K.
08287453	5539153	150	08/08/1994	METHOD OF BUMPING SUBSTRATES BY CONTAINED PASTE DEPOSITION	SCHWIEBERT, MATTHEW K.
08311796	Not Issued	161	09/26/1994	STANDOFF ENHANCEMENT AND CONTROL FOR FLIP CHIP ASSEMBLY THROUGH THE USE OF PAD-LESS BUMPS	SCHWIEBERT, MATTHEW K.
08542243	Not Issued	168	10/11/1995	METHOD OF FABRICATING AND HARVESTING SOLDER POWDER PARTICLES WITH	SCHWIEBERT, MATTHEW K.

				DIAMETER OF LESS THAN TEN(10) MICRONS AND LOW OXIDE CONTENT	
<u>08617585</u>	<u>5586715</u>	150	03/19/1996	METHOD OF MAKING SOLDER BALLS BY CONTAINED PASTE DEPOSITION	SCHWIEBERT, MATTHEW K.
<u>08618225</u>	Not Issued	161	03/19/1996	BUMPED SUBSTRATES BY CONTAINED PASTE DEPOSITION METHOD	SCHWIEBERT, MATTHEW K.
<u>08618226</u>	<u>5672542</u>	150	03/19/1996	METHOD OF MAKING SOLDER BALLS BY CONTAINED PASTE DEPOSITION	SCHWIEBERT, MATTHEW K.
<u>08920221</u>	<u>5880017</u>	150	08/25/1997	METHOD OF BUMPING SUBSTRATES BY CONTAINED PASTE DEPOSITION	SCHWIEBERT, MATTHEW K.
<u>09031864</u>	<u>6239385</u>	150	02/27/1998	SURFACE MOUNTABLE COAXIAL SOLDER INTERCONNECT AND METHOD	SCHWIEBERT, MATTHEW K.
<u>09069262</u>	Not Issued	161	04/29/1998	IRON-NICKEL MASK WITH COEFFICIENT OF THERMAL EXPANSIVITY MATCHING SILICON	SCHWIEBERT, MATTHEW K.
<u>09127531</u>	<u>6137693</u>	150	07/31/1998	HIGH-FREQUENCY ELECTRONIC PACKAGE WITH ARBITRARILY- SHAPED INTERCONNECTS AND INTEGRAL SHIELDING	SCHWIEBERT, MATTHEW K.
<u>09179245</u>	<u>6139972</u>	150	10/26/1998	SOLDER PASTE CONTAINMENT DEVICE	SCHWIEBERT, MATTHEW K.

Inventor Search Completed: No Records to Display.

Search Another: Inventor	Last Name	First Name	<input type="button" value="Search"/>
	<input type="text" value="Schwiebert"/>	<input type="text" value="Matthew"/>	

To go back use Back button on your browser toolbar.

Back to [PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | [Home page](#)

Day : Wednesday

Date: 8/31/2005

Time: 14:04:34


PALM INTRANET
Inventor Name Search Result

Your Search was:

Last Name = MURPHY

First Name = R.

Application#	Patent#	Status	Date Filed	Title	Inventor Name
10742285	Not Issued	30	12/19/2003	Method and system for distribution of an exposure control signal for focal plane arrays	MURPHY, R. ALLEN
06065514	4378629	150	08/10/1979	SEMICONDUCTOR EMBEDDED LAYER TECHNOLOGY INCLUDING PERMEABLE BASE TRANSISTOR FABRICATION METHOD	MURPHY, R. ALLEN
06431055	Not Issued	161	09/30/1982	SEMICONDUCTOR EMBEDDED LAYER TECHNOLOGY	MURPHY, R. ALLEN
07073912	5032538	150	07/07/1987	SEMICONDUCTOR EMBEDDED LAYER TECHNOLOGY UTILIZING SELECTIVE EPITAXIAL GROWTH METHODS	MURPHY, R. ALLEN
07678670	5298787	150	04/01/1991	SEMICONDUCTOR EMBEDDED LAYER TECHNOLOGY INCLUDING PERMEABLE BASE TRANSISTOR	MURPHY, R. ALLEN
07872582	5846708	150	04/23/1992	OPTICAL AND ELECTRICAL METHODS AND APPARATUS FOR MOLECULE DETECTION	MURPHY, R. ALLEN
08448725	5834840	150	05/25/1995	NET-SHAPE CERAMIC PROCESSING FOR ELECTRONIC DEVICES AND PACKAGES	MURPHY, R. ALLEN
08450692	5801073	150	05/25/1995	NET-SHAPE CERAMIC PROCESSING FOR ELECTRONIC DEVICES AND PACKAGES	MURPHY, R. ALLEN

08511649	5653939	150	08/07/1995	OPTICAL AND ELECTRICAL METHODS AND APPARATUS FOR MOLECULE DETECTION	MURPHY, R. ALLEN
09617509	6714945	150	07/17/2000	SYSTEM, METHOD, AND ARTICLE OF MANUFACTURE FOR PROPAGATING TRANSACTION PROCESSING FACILITY BASED DATA AND FOR PROVIDING THE PROPAGATED DATA TO A VARIETY OF CLIENTS	MURPHY, R. CRAIG
07180453	4922922	150	04/12/1988	FLUID MONITORING APPARATUS	MURPHY, R. EDWARD
11153304	Not Issued	20	06/15/2005	Utilities and communication integrator	MURPHY, R. KENNETH
60586786	Not Issued	159	07/09/2004	Utilities and communication integrator	MURPHY, R. KENNETH
60624023	Not Issued	20	11/01/2004	Current sensing lug	MURPHY, R. KENNETH
60624024	Not Issued	20	11/01/2004	Current sensing bar	MURPHY, R. KENNETH
60339701	Not Issued	159	12/13/2001	Modified ceiling fan air freshening article	MURPHY, R. MICHAEL
10808672	Not Issued	30	03/24/2004	Integral insert molded fiber optic transceiver electromagnetic interference shield	MURPHY, R. SEAN
11129138	Not Issued	30	05/13/2005	Monolithic living hinge small form factor transceiver bail-delatch	MURPHY, R. SEAN

Inventor Search Completed: No Records to Display.

Search Another: Inventor

Last Name	First Name
<input type="text" value="MURPHY"/>	<input type="text" value="R."/>

To go back use Back button on your browser toolbar.

Back to [PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | [Home page](#)